Semiautomatic Wire Bonder (wegde & ball) with 3 motorized axes

WB-300-U

- Very compact table top unit, mouse controlled
- Wedge/ Ball Bonden with gold or aluminium wire 17 µm - 50 µm
- Motorzed Deep Access Bondhead
  - – Z-axis 40 mm
  - – Accuracy 1.0 µm
  - – Bond arm length 165 mm
- Motorized X-Y-table
  - – Fine table motion 50 x 50 mm
  - – Accuracy 1.0 µm

Spezifikation

- 250 °C heating chuck with 60 mm diameter
- Motorized wire spool
- EFO: electronic flame-off
- Integrated goose neck with LED
- Ethernet
- Optional with vertical camera

Programmierung

- Bond force I, II und III (security ball)
- Time I, II und III (security ball)
- Power I, II und III (security ball)
- Various loop heights, direct revers
- SIMATIC© control with 7" touch panel
- Start height
- Tail-length and cut off
- Automatic bond height detection
- Temperature
- 32 programs with 50 steps each

WB-300-U [Made in Germany]

UNITEMP
Universal Temperature Processes

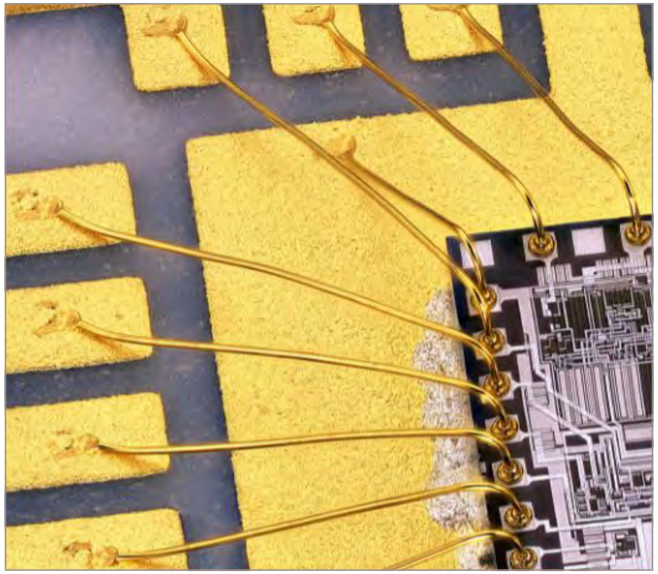
WB-300-U

The WB-300-U is versatile and combines its excellent ergonomic design with high functionality and flexibility.

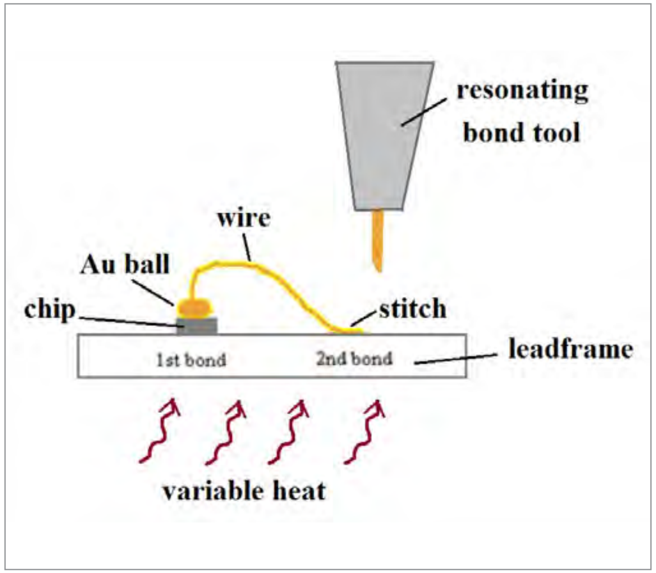
- Inclusive 2-arm LED light source
- inclusive heated chuck (60 mm diameter, height adjustable)
- optional with microscope or camera
- Wedge, Ball, Bump and security ball Bondeing
- 17 µm to 50 µm gold and aluminium wire
- SPS control with 7" Touch Panel
- Deep-access Bond head
- Bond arm length: 165 mm
- 32 programs with 50 steps each storable (export to and import from USB 2.0 memory stick possible)
- heating tool controller
- Mouse controlled Z-,X- and Y-axis
- Motorized wire spool
- Ethernet
- SPS SIMATIC® control with 7" touch panel

Bonding

Either manually with hand lever or semi-automatic with mouse control and via microscope or semi-automatic with mouse control and camera system. Its compact size and weight allows easy transport and setting up of the bonder. By simply changing the tool, the bonder is suitable for wegde or ball bonding.



Wedge bonding



Ball bonding

WB-300-U Basic System/ Scope of Delivery

WB-300-U for wedge and ball bonding (one unit with easy tool change)

- Bonder with 3 motorized axes
- LED light source
- HP-60 heated chuck
- 1 Tool for ball and wedge bonding
- motorized wire spool
- EFO (electronic flame off)

Specification

Basic System with microsocpe, either Motic or Leica.

Option: with manual Z-Tooling

Option: with vertical and horizontal camera system

Technical Data WB-300-U

Bond methods	Wedge, Ball, Bump and secure Ball bonding
Gold wire diameter	17 - 50 µm
Aluminium wire diameter	17 - 50 µm

Ultraonic system	PLL control 62 kHz transducer
Ultrasonic power	0 - 4 Watt
Bond time	5 - 20000 msec.
Bond force	5 - 300 cN
Transducer	Modell WBT140 Wedge and Ball Transducer
Frequency	62 kHz
Total length	185 mm
Horn length	140 mm
Collar length	23 mm
Bond tool	1,58 Dm. 19 mm length (0,0626" x 0,750")

Axes	
Motorized Z-axis	40 mm
Motorized Y-axis	50 mm
Motorized X-axis	50 mm
Mouse ration	programmable

Motorized wire spool Modell MW (50,8 mm, 2")	
Wire termination	Bond Head Tear / Clamp Tear
Wire feed angle	90 °
Clamp movemente	motorized, up and down
Wire strength	12 - 75 µm (2“ wire spool)
Wire control	by infrared sensor and micro controller

Heated chuck Model HP-60	
Heated area	60 mm diameter
Temperature	max. 250 °C
Temp.Accuracy	± 1 %
Height	adjustable 66 - 78 mm

Electrical requirements WB-300-U	
Voltage	100 - 240 V, 50 - 60 Hz
Current	max. 5 A
Dimension	580 x 510 x 490 mm
Weight	45 kg

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